PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
GIL SUNG ROH	09/19/2019
SANG KYUNG KIM	09/19/2019
JI HOON HA	09/20/2019

RECEIVING PARTY DATA

Name:	MAGNACHIP SEMICONDUCTOR, LTD.	
Street Address:	215, DAESIN-RO, HEUNGDEOK-GU	
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State/Country:	tate/Country: KOREA, REPUBLIC OF	
Postal Code:	28429	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16587917

CORRESPONDENCE DATA

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SIGNATURE: /Mark E. Wallerson/

DATE SIGNED: 09/30/2019

Total Attachments: 2

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PATENT 505698949 REEL: 050567 FRAME: 0207

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

DECLARATION

As a below-named inventor, I hereby declare that this declaration is directed to the application attached hereto				
or to United States Application Number or PCT International Application Number				
filed on	(if applicable), entitled:			
RECEPTION DEVICE, OPERATING METHOD, AND TRANSMISSION SYSTEM WITH SWITCHING NOISE REDUCTION				

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

ASSIGNMENT

For valuable consideration, I, as a below-named assignor, hereby assign to:

MagnaChip Semiconductor, Ltd. 215, Daesin-ro, Heungdeok-gu Cheongju-si, Chungcheongbuk-do, 28429 Republic of Korea

interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number 16/587,917 filed on September 30, 2019	and its suc	cessors and assigns (collect	ively hereina	after called "the Assignee"), the entire right, title, and
4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4	interest thro	oughout the world in the inve	ntions and i	improvements that are the subject of the application
Number 16/587,917 filed on September 30, 2019	identified in	the above declaration, whic	h is United	States Application Number or PCT International Application
	Number	16/587,917	_ filed on	September 30, 2019

I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

This Assignment includes the above-identified application, any and all continuation applications and divisional applications claiming the benefit of the above-identified application under the United States patent laws, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filling date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

Inventor's Legal Name	Gil Sung ROH			
Inventor's Signature		Date	2019/9/19	
Residence (City, Country)	Cheongju-si, Republic of Korea			
Mailing Address	c/o MagnaChip Semiconductor, Ltd., 215, Daesin-ro, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28429 Republic of Korea			
MAN AREA PROPERTY AND AREA PRO				
Inventor's Legal Name	Sang Kyung KIM			
Inventor's Signature	Alm	Date	2019, 9.19.	
Residence (City, Country)	Cheongju-si, Republic of Korea			
Mailing Address	c/o MagnaChip Semiconductor, Ltd., 215, Daesin-ro, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28429 Republic of Korea			
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Inventor's Legal Name	Ji Hoon HA			
Inventor's Signature	3/1/3	Date	2019. 9.20	
Residence (City, Country)	Cheongju-si, Republic of Korea			
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